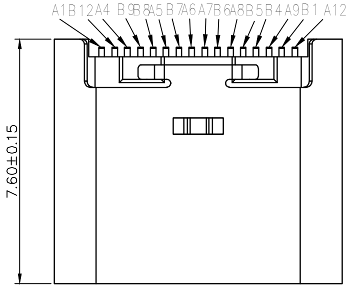
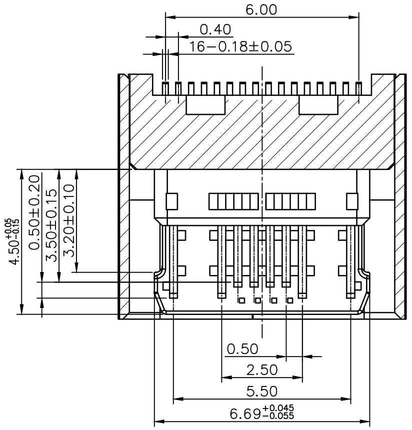
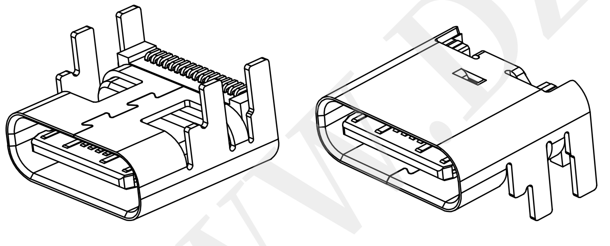
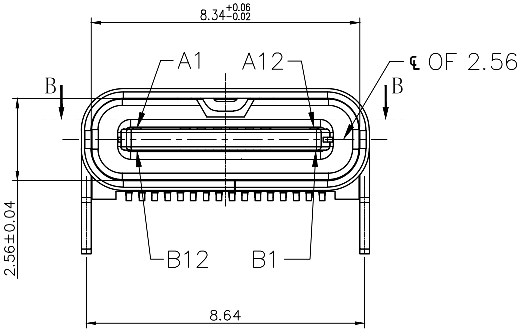
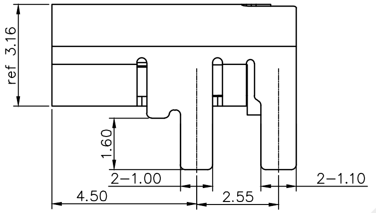
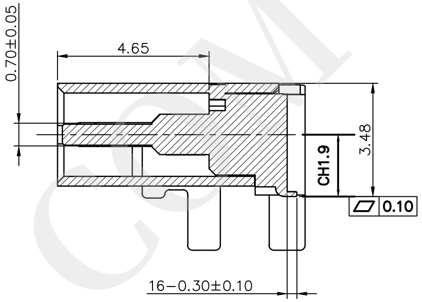




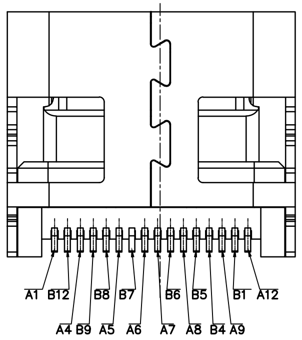


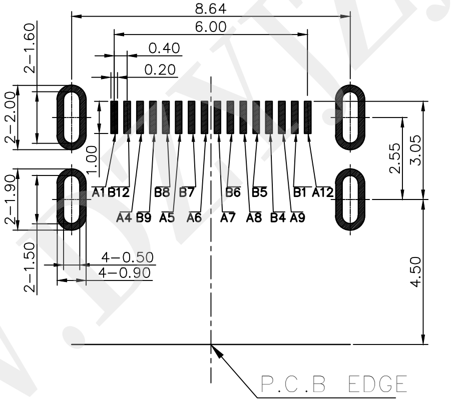






SECTION B-B
SCALE 1:1





RECOMMEND P.C.B LAYOUT(COMPONENT SIDE)

TOLERANCE FOR PCB LAYOUT IS ± 0.05

NOTE:

1.MATERIAL SPECIFICATION:
- 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC.
- 2.CONTACTS:COPPER ALLOY
- 3.SHELL:STAINLESS STEEL
- 4.MID PLATE: STAINLESS STEEL

2.PLATING SPECIFICATION:
- 2-1.CONTACTS:
  - Ni 50u" MIN. UNDER PLATED OVER ALL.
  - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
  - (GOLD PLATING THICKNESS FOLLOW THE P/N)
  - GOLD FLASH PLATING ON SOLDER AREA
- 2-2.FRONT SHELL:
  - Ni 30u" MIN. UNDER PLATED OVER ALL.

3.MECHANICAL PERFORMANCE,
- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,
- 4-1. CURRENT RATING:5.0A
  VOLTAGE RATING:20V
- 4-2.INSULATION RESISTANCE: 100MΩ MIN
- 4-3.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
- 4-4.LOW CONTACT RESISTANCE: INITIAL 40MΩ
  AFTER 50MΩ

5. ENVIRONMENTAL PERFORMANCE:
- OPERATING TEMPERATURE: -30℃~+80℃.

6.IR REFLOW:
- THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260℃.

3	外壳	不锈钢	镀镍	
2	接触	铜	镀金	
1	基座	LCP	黑色	
序 号	品 名	材 质	电镀/颜色	备 注

HOAUC 华宇创

深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.° ±2° X.X° ±0.5°	DRAWED BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB TYPE C 母座16P 板上SMT L=7.6 垫高0.3 CH=1.9
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC684-USBC16-760
			MOLD NO.
UNIT: mm [inch]	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2602100902
SCALE:1:1 SIZE: A4			SHEET NO. 1 OF 1